

WHAT IS CLAIMED IS:

1. A semiconductor light-emitting element comprising:
a chip having at least an electrode and a protective film layer;
an insulating resin for sealing said chip;
wherein said insulating resin is hardened at high temperature and heat-treated in an atmosphere having humidity.
2. A semiconductor light-emitting element according to claim 1, wherein the heat treatment is performed at a temperature of 60°C or higher.
3. A semiconductor light-emitting element according to claim 1, wherein the atmosphere has an absolute humidity of not less than 10 KPa.
4. A semiconductor light-emitting element according to claim 2, wherein the atmosphere has an absolute humidity of not less than 10 KPa.
5. A semiconductor light-emitting element according to claim 1, wherein the atmosphere has an absolute humidity of not less than 50 KPa.

6. A semiconductor light-emitting element according to claim 2, where the atmosphere has an absolute humidity of not less than 50 KPa.

7. A semiconductor light-emitting element according to claim 1, wherein the heat treatment is performed at a pressure of 1 atm or higher.

8. A semiconductor light-emitting element according to claim 2, wherein the heat treatment is performed at a pressure of 1 atm or higher.

9. A semiconductor light-emitting element according to claim 3, wherein the heat treatment is performed at a pressure of 1 atm or higher.

10. A semiconductor light-emitting element according to claim 4, wherein the heat treatment is performed at a pressure of 1 atm or higher.

11. A semiconductor light-emitting element according to claim 5, wherein the heat treatment is performed at a pressure of 1 atm or higher.

12. A semiconductor light-emitting element according to claim 6, wherein the heat treatment is performed at a pressure of 1 atm or higher.

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